MA2Z784 (MA784)

Silicon epitaxial planar type

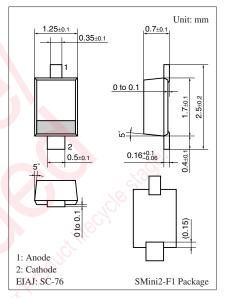
For super high speed switching For small current rectification

Features

- High-density mounting is possible
- Forward current (Average) $I_{F(AV)} = 100 \text{ mA}$ rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- Low forward voltage V_F and good rectification efficiency

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Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	30	V
Repetitive peak reverse voltage	V _{RRM}	30	V
Peak forward current	I _{FM}	300	mA
Forward current (Average)	I _{F(AV)}	100	mA
Non-repetitive peak forward surge current *	I _{FSM}	1	A
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C





Marking Symbol: 2D

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

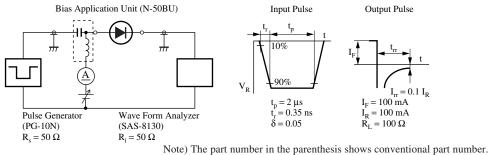
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	I _F = 100 mA	0		0.55	V
Reverse current	Ι _R	$V_R = 30 V$	N.X		15	μA
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		20		pF
Reverse recovery time *	t _{rr}	$I_{\rm F} = I_{\rm R} = 100 \text{ mA}$		2.0		ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

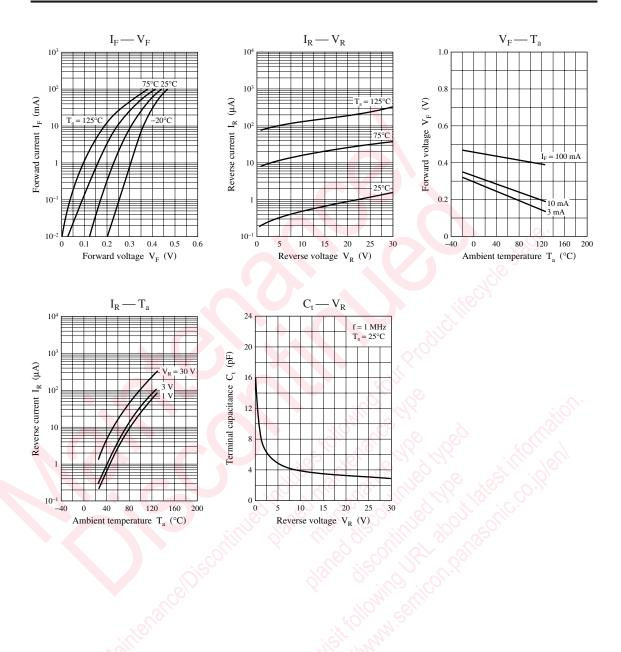
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz.

4.*: t_{rr} measurement circuit



Panasonic



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